

1 WHAT IS CLAIMED IS:

2

3 1. An optical to electrical or electrical to optical conversion assembly,

4 comprising:

5 a substrate having a surface onto which components of said conversion

6 assembly are attached; and

7 a flexible circuit operatively and electrically attached to said surface.

8

9 2. The conversion assembly of claim 1, wherein said components are selected

10 from the group consisting of optical components and electrical components.

11

12 3. The conversion assembly of claim 1, wherein said conversion assembly is

13 selected from the group consisting of an optical to electrical conversion assembly (OECA) and

14 an electrical to optical conversion assembly (EOCA).

15

16 4. The conversion assembly of claim 3, wherein said conversion assembly

17 comprises an optical wavelength division multiplexer and demultiplexer for single-mode or

18 multi-mode fiber optic communication systems.

19

20 5. The conversion assembly of claim 3, wherein said surface comprises a low

22

23 6. The conversion assembly of claim 5, wherein said surface comprises a

24 thermal conductivity rating of about at least 25 W/m K.

25

26

1 7. The conversion assembly of claim 6, wherein said surface comprises a
2 ceramic material.

3
4 8. The conversion assembly of claim 7, wherein said ceramic material is
5 selected from the group consisting of BeO, AlN, or Al₂O₃.

6
7 9. The conversion assembly of claim 8, wherein said components are attached
8 to said surface utilizing a thick film process to deposit metal on said substrate for attachment
9 of optical conversion circuits, routing of signals and gold bond wire attachment.

10
11 10. The conversion assembly of claim 8, wherein said substrate undergoes a
12 subtractive etch process and then is copper plated.

13
14 11. The conversion assembly of claim 8, wherein said conversion assembly
15 comprises said OECA, wherein electrical connections are made from said flexible circuit to
16 said components with gold bond wire.

17
18 12. The conversion assembly of claim 8, wherein said conversion assembly
19 comprises said EOCA, wherein electrical connections are made from said flexible circuit to

21
22 13. The conversion assembly of claim 1, wherein said flexible circuit is
23 electrically attached to at least one component of said components to form an operation
24 circuit, wherein said operation circuit comprises means for achieving low loss transmission
25 of an electrical signal propagating on said operation circuit.

26

1 14. The conversion assembly of claim 13, wherein said means for achieving low
2 loss transmission comprises a transmission media that is selected from the group consisting
3 of coaxial cable, microstrip and stripline.

4
5 15. The conversion assembly of claim 14, wherein said transmission media
6 comprises a transmission frequency within a range from 1 MHz to 20 GHz.

7
8 16. The conversion assembly of claim 13, wherein said means for achieving low
9 loss transmission comprises a waveguide transmission media comprising a transmission
10 frequency of at least about 500 MHz.

11
12 17. The conversion assembly of claim 13, wherein said means for achieving low
13 loss transmission of an electrical signal propagating on said operation circuit are selected
14 from the group consisting of reducing reflections, lowering absorptive loss, preventing cross
15 talk between adjacent signal lines, reducing ringing and reducing standing waves that result
16 from signal reflections.

17
18 18. The conversion assembly of claim 13, wherein said means for achieving low
19 loss transmission comprises providing said operation circuit with a transmission line having
20

21 of said transmission line are cancelled out, wherein said transmission line has no imaginary
22 impedance component.

23

24

25

26

1 19. The conversion assembly of claim 13, wherein said operation circuit
2 comprises a transmission line, wherein a source and a load are operatively connected to said
3 transmission line, wherein said source and said load each present an impedance to said
4 transmission line that match the impedance of said transmission line.

5
6 20. The conversion assembly of claim 1, wherein said flexible circuit comprises
7 a flexible layer.

8
9 21. The conversion assembly of claim 20, wherein a crosshatched ground plane
10 is attached to said flexible layer.

11
12 22. The conversion assembly of claim 21, further comprising a conductive signal
13 layer attached to said flexible layer on the opposite side of said flexible layer with respect to
14 said cross hatched ground plane.

15
16 23. The conversion assembly of claim 22, further comprising an outer solder
17 mask layer on said cross hatched ground plane and another outer solder mask layer on said
18 conductive signal layer.

19
20 24. The conversion assembly of claim 20, wherein said flexible layer comprises
21 polyimide.

22
23 25. The conversion assembly of claim 20, wherein said flexible layer comprises
24 polyimide, wherein said polyimide is about .0020 inches thick.

25
26

1 26. The conversion assembly of claim 23, wherein at least one solder mask layer
2 comprises a liquid photo imageable solder mask.

3
4 27. The conversion assembly of claim 13, wherein said operation circuit
5 comprises a transmission line terminated with a VCSEL diode and series resistor such that
6 the nominal impedance of said transmission line matches the combined impedance of said
7 VCSEL and said series resistor.

8
9 28. The conversion assembly of claim 27, wherein said VCSEL is a current mode
10 device and is powered by laser driver circuitry operating as a current source off of a fixed
11 supply rail of 5V, wherein there is no additional total power loss with the use of said matching
12 resistor, wherein power that would have been dissipated in the laser driver circuit if there were
13 no matching resistor is now dissipated in said resistor.

14
15
16
17
18
19
20
21
22
23
24
25
26

1 29. A method of fabricating a ceramic substrate for use in an optical to electrical
2 or electrical to optical conversion assembly, comprising:
3 providing a sheet of ceramic material;
4 lapping said sheet down to a desired thickness of about .035 inches;
5 drilling all necessary holes in said sheet;
6 cleaning and pre-firing said sheet in a convection oven that slowly ramps the
7 material up to 850 to 900 degrees C;
8 applying a PdAg paste to said sheet;
9 baking said sheet at 100 to 150 degrees C to remove the solvents from said
10 paste;
11 firing said sheet in a convection oven that slowly ramps the temperature to
12 between 850 and 900 degrees C to anneal said paste;
13 allowing said sheet to cool;
14 printing gold pads and traces onto said sheet;
15 baking said sheet at 100 to 150 degrees C to remove the solvents from said
16 gold pads and traces;
17 firing said sheet in a convection oven that slowly ramps the temperature to
18 between 850 and 900 degrees C to anneal said gold pads and traces;
19 depositing a resistive paste is said ceramic surface in the required geometry;
20 and

22
23 30. A method of fabricating a flexible high speed transmission line for use in an
24 optical to electrical or electrical to optical conversion assembly, comprising:
25 providing a sheet of about .002 inch thick polyimide material;
26 depositing and annealing copper on both sides of said sheet;

1 cutting all the required vias and holes in said sheet;
2 plating said sheet with copper to fill in said vias and holes;
3 strengthening the connections of said vias with an additional electroplated
4 copper plating sequence;
5 applying dry film photoresist to both sides of said sheet;
6 applying negative image films of desired copper traces and cross hatched
7 ground to both sides of the panel;
8 removing the resist from the areas where the copper is to be removed;
9 placing said sheet in an alkaline etching bath where unwanted copper is
10 removed from said sheet and the remaining photoresist is then stripped away leaving copper
11 only where traces and cross hatched ground are desired;
12 coating said sheet with liquid photoimageable solder mask;
13 placing said sheet in an oven at about 170 to 180 degrees C for about 15
14 minutes;
15 placing a negative image film of a solder mask layer on the top and bottom
16 of said sheet and exposing said sheet to ultra violet light, wherein the areas exposed to the
17 light are polymerized and become resistant to the developer;
18 placing said sheet in a developer bath, wherein the solder mask is removed
19 from those areas of the board that were not exposed to the ultra violet light;
20 baking said sheet at about 300 degrees C for about 1 hour to completely cure
21
22 plating the exposed copper on said sheet using an electroless Nickel plating
23 process; and
24 plating said sheet with gold.
25

26 9257.100

911